



Final Product/Process Change Notification

Document #:FPCN25572XP

Issue Date:26 Jun 2026

Title of Change:	Update of FPCN25572X - LVX_245 Transceivers, SOICW package, Vanguard FAB Transfer and assembly bond wire change.	
Proposed First Ship date:	03 Oct 2026 or earlier if approved by customer	
Contact Information:	Contact your local onsemi Sales Office	
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Additional Reliability Data:	Contact your local onsemi Sales Office	
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com	
Marking of Parts/ Traceability of Change:	Date Code; MC74LVXC3245DWRG is changing to new OPN MC74LVXC3245DWR2G	
Change Category:	Wafer Fab Change, Assembly Change	
Change Sub-Category(s):	Material Change, Manufacturing Site Transfer, Datasheet/Product Doc change	
Sites Affected:		
onsemi Sites	External Foundry/Subcon Sites	
onsemi Carmona, Philippines	Vanguard International Semiconductor, Taiwan	
Description and Purpose:		
This is to notify customers of FAB manufacturing transfer from Tower to Vanguard Fab and will use 200mm wafers. Current assembly site will convert from 0.8mil Gold to 1.0 PCC bond wire for all affected products.		
This change will include an update to the datasheet for Absolute max DC supply voltage range.		
FAB Change	Before	After
Fab Site	Tower	Vanguard
Wafer Diameter	150mm	200mm
Assembly Change	Before	After
Bond Wire	0.8mil Au	1.0 mil PCC
Electrical Parameter Change		
Change	Before	After
Abs Max DC Supply Voltage – Datasheet update	-0.5 to +7.0 V	-0.5 to +6.5V



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Reliability Data Summary:

QV DEVICE NAME : MC74LVXC3245DWR2G

RMS : O105297

PACKAGE : SOICW 24

Test	Specification	Condition	Interval	Result Rej/SS
High Temperature Operating Life	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs	0/240
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs	0/240
Preconditioning	J-STD-020 JESD-A113	MSL 3 @ 260°C, Pre TC, uHAST, HAST for surface mount pkgs only	-	Pass
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	1000 cyc	0/240
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	192 hrs	0/234
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/240

QV DEVICE NAME : MC74LVXC4245DTR2G-Q

RMS : O105269

PACKAGE : TSSOP 24

Test	Specification	Condition	Interval	Result Rej/SS
High Temperature Operating Life	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs	0/80

Electrical Characteristics Summary:

Electrical characteristics are not impacted, with the exception to the Abs Max DC Supply Voltage update in the datasheet.

Datasheets linked to onsemi.com (will be updated on Production release)

[MC74LVX3254](#)

[MC74LVX4245](#)

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Current Part Number	New Part Number	Qualification Vehicle
MC74LVXC3245DWRG	MC74LVXC3245DWR2G	MC74LVXC3245DWR2G
MC74LVX4245DWR2G	#NONE	MC74LVX4245DTR2G-Q, MC74LVXC3245DWR2G